

EXHIBIT 6

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Partial Translation

JP Patent Application Disclosure No. 2001-287152 – 16 October 2001

Application No. 2000-108791 – 11 April 2000

Applicant: ACHILLES CORPORATION, Tokyo (JP)

Title: POLISHING SHEET FOR SEMICONDUCTOR WAFER AND
METHOD FOR MANUFACTURING THE SAME

[Descriptive part of the specification]

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[0014]

Examples of the polishing material in the form of fine powder used in the polishing sheet for semiconductor wafers provided by the present invention in this case include: silica oxide, silicon oxide, aluminum oxide, zirconium oxide, cerium oxide, titanium oxide, chromium oxide, silicon carbide, boron nitride, glass fibers, alumina fibers, alumina-silica fibers, silica fibers, boron fibers, carbide fibers, and silicon carbide. Among these, silica oxide and cerium oxide are preferred.

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ABRASIVE SHEET FOR SEMICONDUCTOR WAFER AND MANUFACTURING METHOD THEREFOR

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Applicant(s): ACHILLES CORP +

Classification:

- international: *B24B37/00; C08J5/14; C08J9/40; C08K3/00; C08L75/04; C09K3/14; H01L21/304; B24B37/00; C08J5/14; C08J9/00; C08K3/00; C08L75/00; C09K3/14; H01L21/02; (IPC1-7): B24B37/00; C08J5/14; C08J9/40; C08K3/00; C08L75/04; C09K3/14; H01L21/304*

- European:

Application number: JP20000108791 20000411

Priority number(s): JP20000108791 20000411

Abstract of JP 2001287152 (A)

PROBLEM TO BE SOLVED: To provide an abrasive sheet for semiconductor wafers with flatly and closely processed surface, with abrasive uniformly added, and with low elasticity, thereby capable of strongly pressed polishing, without damaging a semiconductor substrate in polishing. **SOLUTION:** This abrasive sheet for semiconductor wafers manufactured by impregnating and attaching urethane based emulsion resin liquid with fine- powder abrasive uniformly dispersed into soft polyurethane foam or semi-hard polyurethane foam, especially its surface, and by compression molding into a resin form.

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